

### Silicon Carbide MOSFET

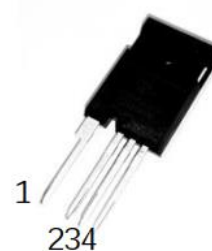
#### DESCRIPTION :

- Low gate charge
- Low Switching Losses
- Fast reverse recovery body diode
- Fast High frequency operation
- Tight variation of  $R_{DS(on)}$  with temperature

$V_{DS}$	1200V
$I_D (T_c = 25^\circ\text{C})$	87.5A
$R_{DS(on)}$	40m $\Omega$

#### TYPICAL APPLICATIONS :

- Energy Storage
- Uninterruptible power supplies (UPS)
- Motor drives
- Switch mode power supplies
- Solar inverters
- EV Storage



TO-247-4L

#### MAXIMUM RATINGS (at $T_J = 25^\circ\text{C}$ , unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Drain-Source Voltage		$V_{DSS}$	1200	V
Gate-Source Voltage Recommend Drive Voltage	Max Transient Voltage, <1% duty cycle	$V_{GSS}$ $V_{GS(OP)}$	-10/+22 -3/+18	V
Continuous Drain Current	$V_{GS}=18\text{V}$ , $T_c=25^\circ\text{C}$ $V_{GS}=18\text{V}$ , $T_c=110^\circ\text{C}$	$I_D$	87.5 64.2	A
Pulsed Drain Current	Pulse width tp limited by $T_{jmax}$ , $V_{GS} = 18\text{V}$	$I_{D PULSE}$	140	A
Total power dissipation	$T_c=25^\circ\text{C}$ $T_c=110^\circ\text{C}$	$P_{tot}$	536 232	W
Operation Junction temperature		$T_j$	-55~+175	$^\circ\text{C}$
Storage temperature		$T_{STG}$	-55~+150	$^\circ\text{C}$
Soldering Temperature	1.6mm (0.063") from case for 10s	$T_L$	260	$^\circ\text{C}$
Mounting torque	M3 screw	M	1	Nm

## THERMAL CHARACTERISTICS

Characteristic	Condition	Symbol	Typical	Unit
Thermal resistance, junction - case		$R_{th(j-c)}$	0.28	$^{\circ}\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS (at  $T_J = 25^{\circ}\text{C}$ , unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage $V_{GS} = 0\text{V}$ , $I_D = 100\mu\text{A}$	$V_{(BR)DSS}$	1200			V
Zero Gate Voltage Drain Current $V_{DS} = 1200\text{V}$ , $V_{GS} = 0\text{V}$ $T_J = 25^{\circ}\text{C}$ $V_{DS} = 1200\text{V}$ , $V_{GS} = 0\text{V}$ $T_J = 175^{\circ}\text{C}$	$I_{DSS}$		0.08 11.09	100	$\mu\text{A}$
Gate-Source Leakage Current $V_{GS} = 22\text{V}$ , $V_{DS} = 0\text{V}$ $V_{GS} = -10\text{V}$ , $V_{DS} = 0\text{V}$	$I_{GSS}$			100 100	nA
Gate-Source Threshold Voltage $V_{DS} = V_{GS}$ , $I_D = 10\text{mA}$ $T_J = 25^{\circ}\text{C}$ $V_{DS} = V_{GS}$ , $I_D = 10\text{mA}$ $T_J = 175^{\circ}\text{C}$	$V_{GE(th)}$	2	3.14 2.13	5	V
Drain-Source On-State Resistance $V_{GS} = 18\text{V}$ , $I_D = 35\text{A}$ $T_J = 25^{\circ}\text{C}$ $V_{GS} = 18\text{V}$ , $I_D = 35\text{A}$ $T_J = 175^{\circ}\text{C}$	$R_{DS(on)}$		39 58	60	m $\Omega$
Transconductance $I_D = 30\text{A}$ $T_J = 25^{\circ}\text{C}$ $I_D = 30\text{A}$ $T_J = 175^{\circ}\text{C}$	$G_{fs}$		13.2 13.9		S
Internal Gate Resistance $f = 1\text{MHz}$ , $V_{AC} = 25\text{mV}$	$R_{G(int)}$		1.35		$\Omega$
Input capacitance $f = 1\text{MHz}$ , $V_{AC} = 25\text{mV}$ , $V_{DS} = 800\text{V}$ , $V_{GS} = 0\text{V}$	$C_{iss}$		3726		pF
Output capacitance $f = 1\text{MHz}$ , $V_{AC} = 25\text{mV}$ , $V_{DS} = 800\text{V}$ , $V_{GS} = 0\text{V}$	$C_{oss}$		214		pF
Reverse transfer capacitance $f = 1\text{MHz}$ , $V_{AC} = 25\text{mV}$ , $V_{DS} = 800\text{V}$ , $V_{GS} = 0\text{V}$	$C_{rss}$		19		pF
$C_{oss}$ Stored Energy $f = 1\text{MHz}$ , $V_{AC} = 25\text{mV}$ , $V_{DS} = 800\text{V}$ , $V_{GS} = 0\text{V}$	$E_{oss}$		140		$\mu\text{J}$
Total Gate Charge $V_{DD} = 800\text{V}$ , $I_D = 30\text{A}$ , $V_{GS} = -3/18\text{V}$ , turn-on pulse	$Q_G$		227		nC

Gate to Source Charge VDD= 800V, ID= 30A,VGS= -3/18V, turn-on pulse	$Q_{GS}$		40		nC
Gate to Drain Charge VDD= 800V, ID= 30A,VGS= -3/18V, turn-on pulse	$Q_{GD}$		80		nC
Turn-on delay time VDD=800 V, ID=30A, VGS= -3/18V, $R_{G(EXT)}=4.7\Omega$ $L_\sigma = 100\mu H$ , Body diode at VGS = -3V (inductive load)	$t_{d(ON)}$		26.5		ns
Rise time VDD=800 V, ID=30A, VGS= -3/18V, $R_{G(EXT)}=4.7\Omega$ $L_\sigma = 100\mu H$ , Body diode at VGS = -3V (inductive load)	$t_r$		42.2		ns
Turn-off delay time VDD=800 V, ID=30A, VGS= -3/18V, $R_{G(EXT)}=4.7\Omega$ $L_\sigma = 100\mu H$ , Body diode at VGS = -3V (inductive load)	$t_{d(OFF)}$		43.7		ns
Fall time VDD=800 V, ID=30A, VGS= -3/18V, $R_{G(EXT)}=4.7\Omega$ $L_\sigma = 100\mu H$ , Body diode at VGS = -3V (inductive load)	$t_f$		13.7		ns
Turn-on Switching Energy VDD=800 V, ID=30A, VGS= -3/18V, $R_{G(EXT)}=4.7\Omega$ $L_\sigma = 100\mu H$ , Body diode at VGS = -3V (inductive load)	$E_{(ON)}$		644.7		$\mu J$
Turn-off Switching Energy VDD=800 V, ID=30A, VGS= -3/18V, $R_{G(EXT)}=4.7\Omega$ $L_\sigma = 100\mu H$ , Body diode at VGS = -3V (inductive load)	$E_{(OFF)}$		191.2		$\mu J$
Total Switching Energy VDD=800 V, ID=30A, VGS= -3/18V, $R_{G(EXT)}=4.7\Omega$ $L_\sigma = 100\mu H$ , Body diode at VGS = -3V (inductive load)	$E_{(TOT)}$		835.8		$\mu J$

## Body Diode

ELECTRICAL CHARACTERISTICS (at  $T_J = 25^\circ C$ , unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Diode Forward Voltage VGS = 0V, ISD = 20A $T_J=25^\circ C$ VGS = 0V, ISD = 20A $T_J=175^\circ C$	$V_{SD}$		3.57 3.27		V

Continuous Diode Forward Current VGS = -3V, Tj=25°C VGS = -3V, Tj=100°C	ISD			80 46	A
Revers Recovery Time VDD=800 V, ID=30A, VGS= -3V, di/dt = 1000A/us Tj=25°C	Trr		24.2		ns
Revers Recovery Charge VDD=800 V, ID=30A, VGS= -3V, di/dt = 1000A/us Tj=25°C	Qrr		144		nC
Peak Revers Recovery Current VDD=800 V, ID=30A, VGS= -3V, di/dt = 1000A/us Tj=25°C	Irrm		9.26		A

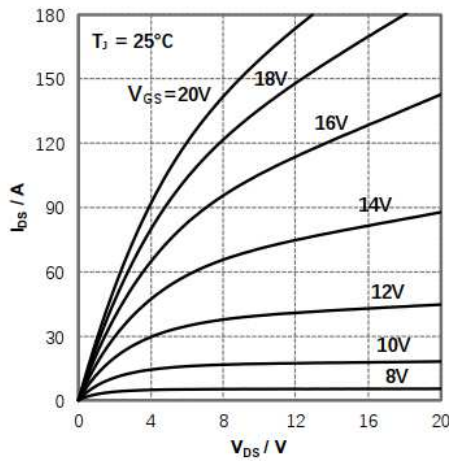


Figure 1. Typical output characteristics (Tj=25°C)

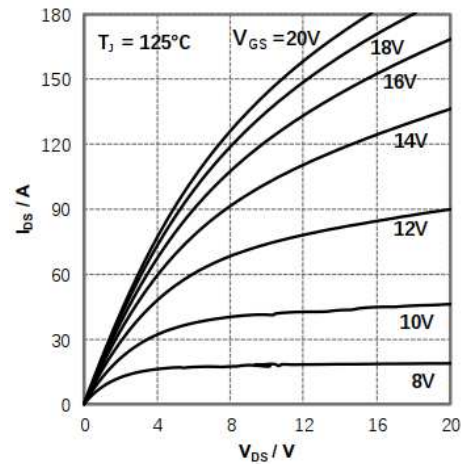


Figure 2. Typical output characteristics (Tj=125°C)

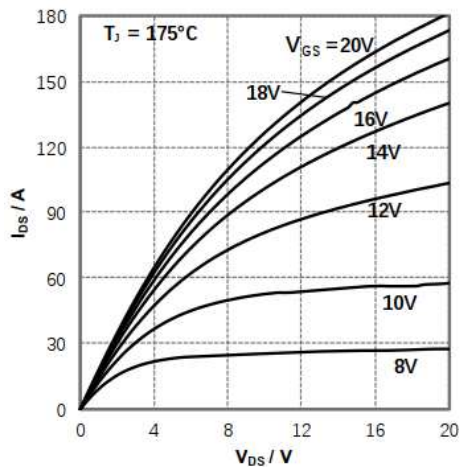


Figure 3. Typical output characteristics (Tj=175°C)

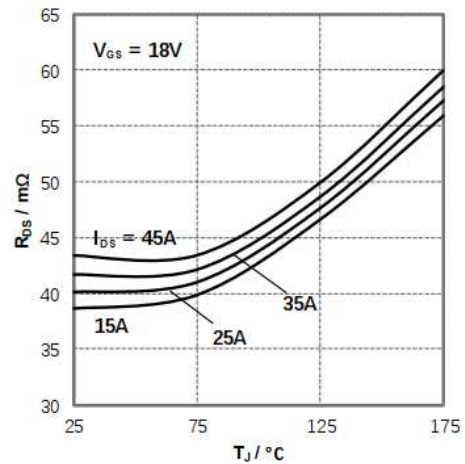


Figure 4. Typical On-Resistance vs. Temperature For Various Drain Current)

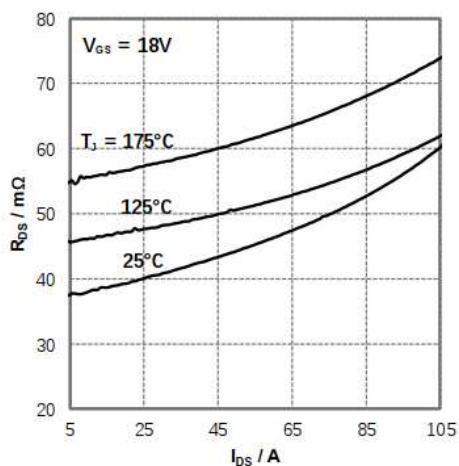


Figure 5. On-Resistance vs. Drain Current For Various Temperature

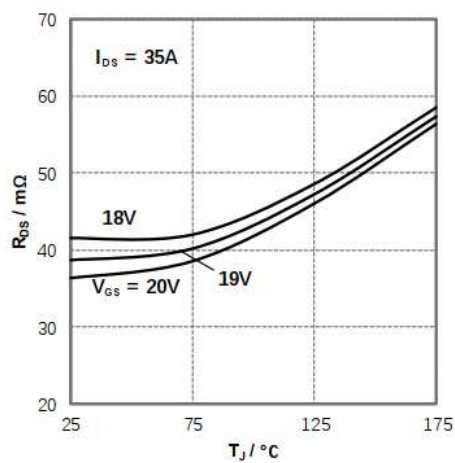


Figure 6. On-Resistance vs. Temperature For Various Gate Voltage

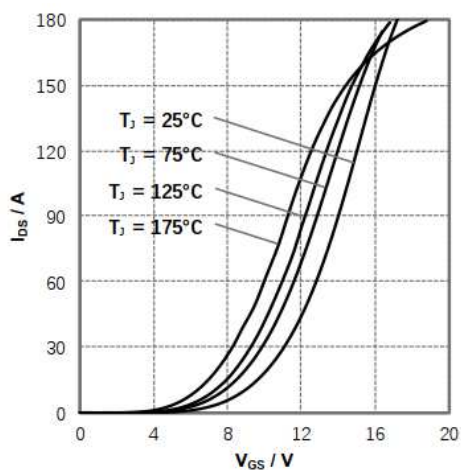


Figure 7. Transfer Characteristics

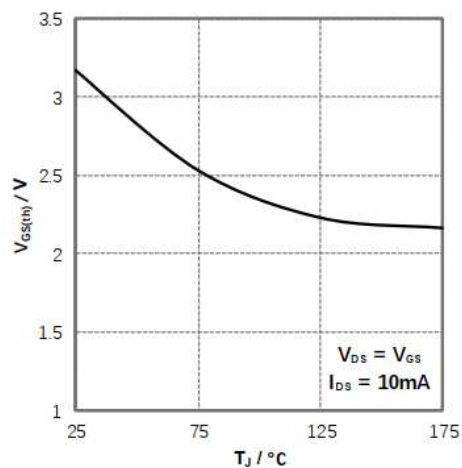


Figure 8. Threshold Voltage vs. Temperature

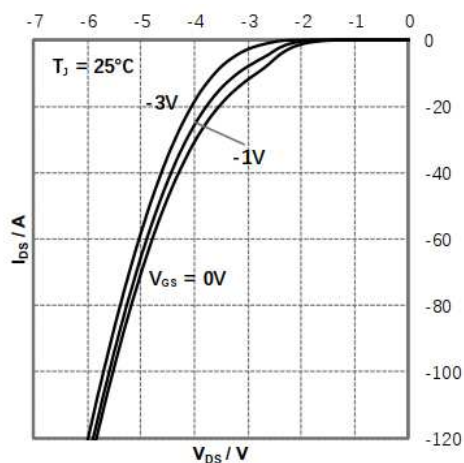


Figure 9. Body Diode Characteristics  $T_J=25^{\circ}\text{C}$

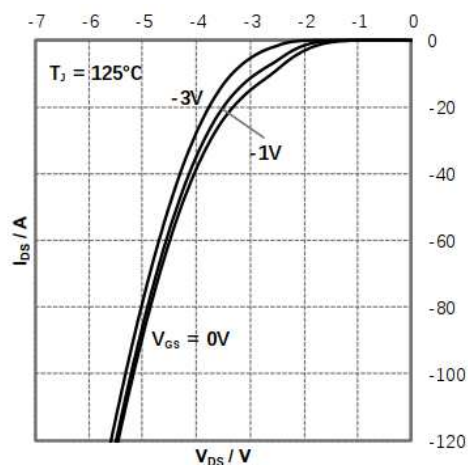


Figure 10. Body Diode Characteristics  $T_J=125^{\circ}\text{C}$

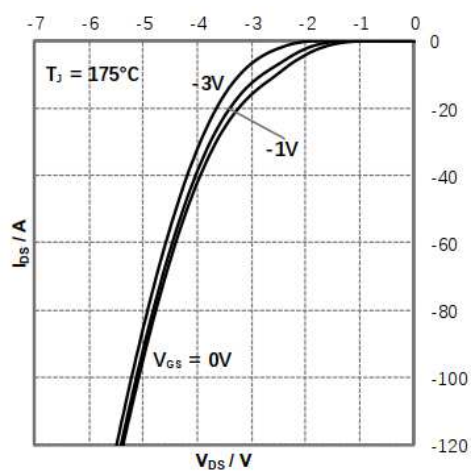
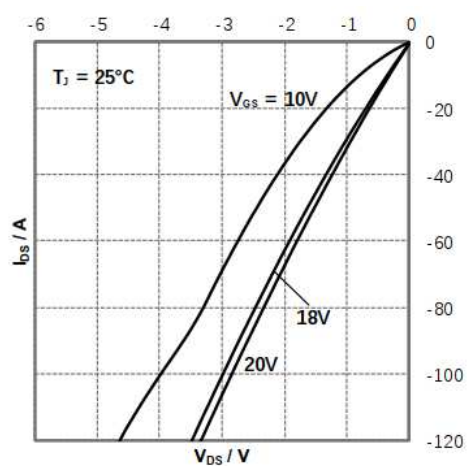
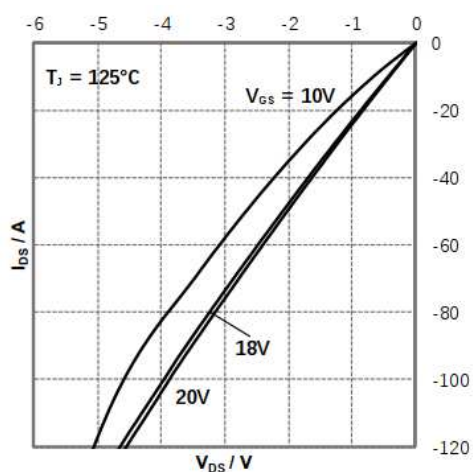
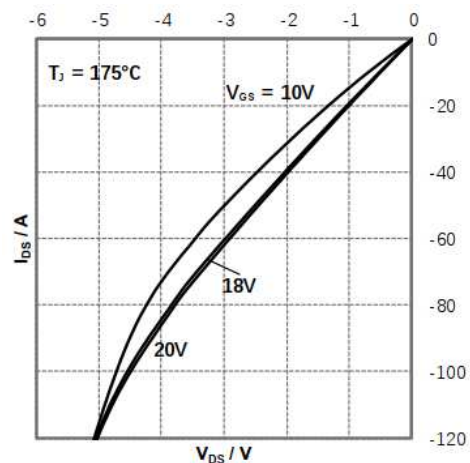
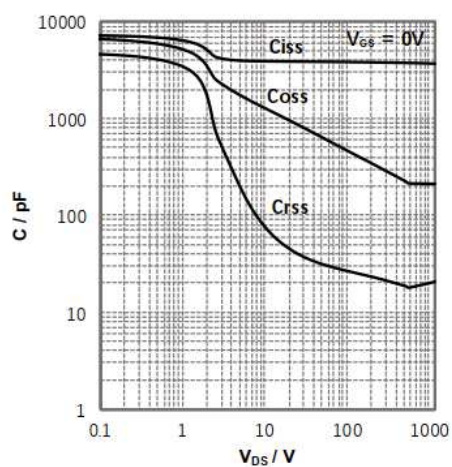
Figure 11. Body Diode Characteristics  $T_J = 175^\circ\text{C}$ Figure 12. 3rd Quadrant Characteristics  $T_J = 25^\circ\text{C}$ Figure 13. 3rd Quadrant Characteristics  $T_J = 125^\circ\text{C}$ Figure 14. 3rd Quadrant Characteristics  $T_J = 175^\circ\text{C}$ 

Figure 15. Capacitances vs. Drain-Source Voltage

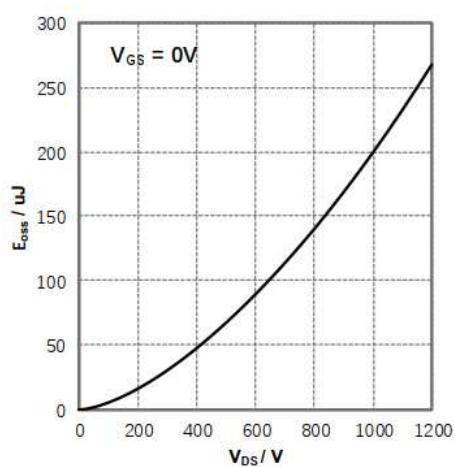


Figure 16. Output Capacitor Stored Energy



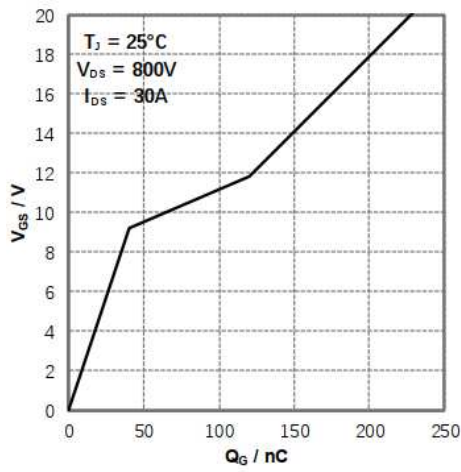


Figure 17. Gate Charge Characteristics

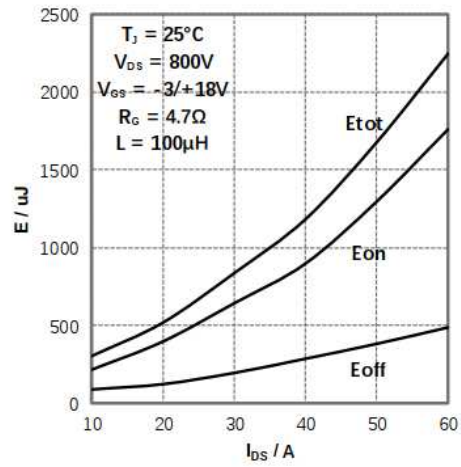


Figure 18. Switching Energy vs. Drain Current

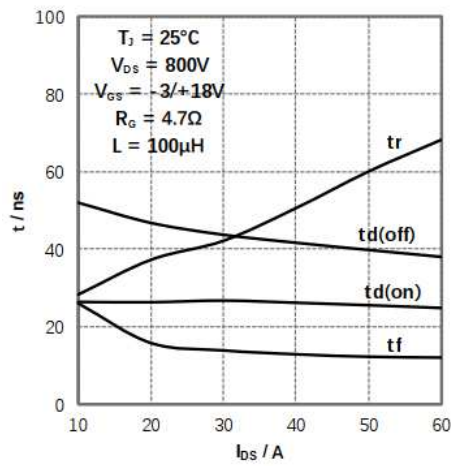


Figure 19. Switching Time vs. Drain Current

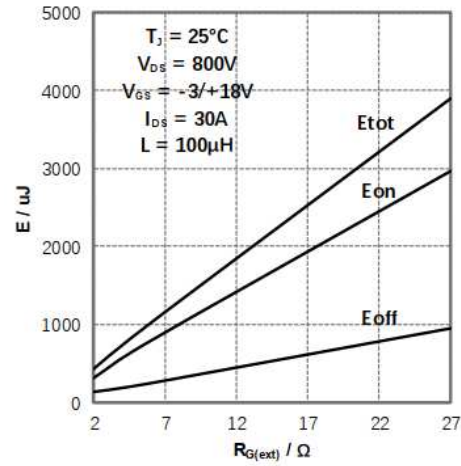


Figure 20. Switching Energy vs.  $R_{G(ext)}$

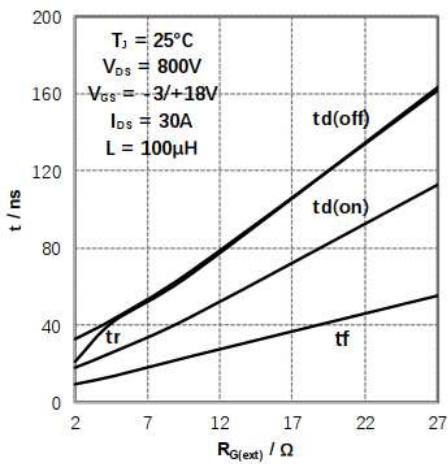


Figure 21. Switching Time vs.  $R_{G(ext)}$

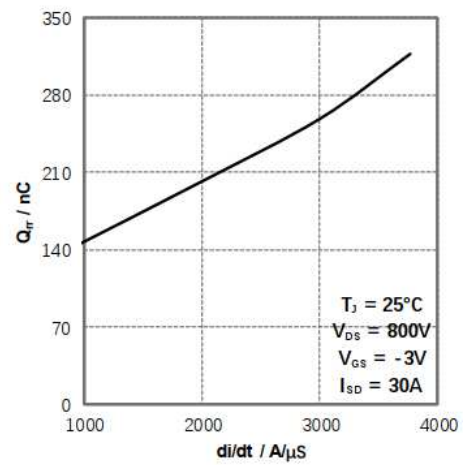


Figure 22. Reverse Recovery Charge vs.  $di/dt$

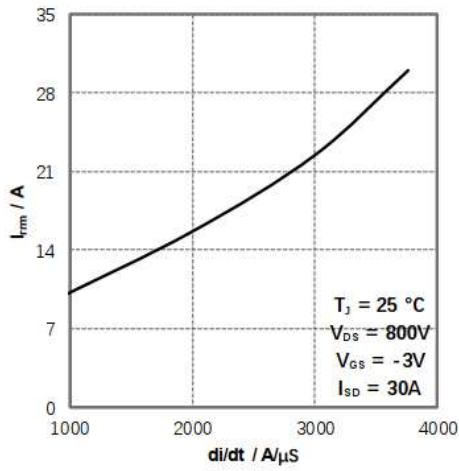


Figure 23. Reverse Recovery Current vs.  $di/dt$

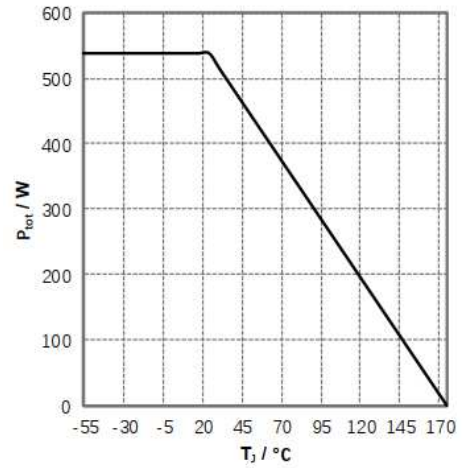


Figure 24. Power Dissipation Derating

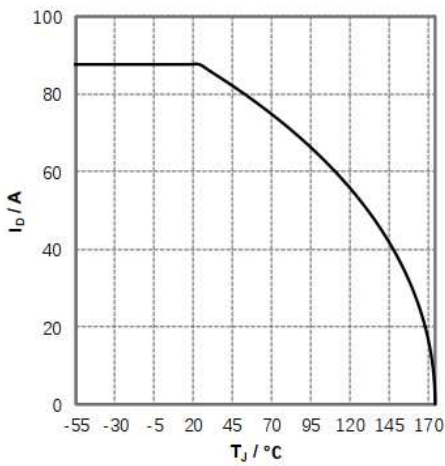


Figure 25. Continuous Drain Current Derating

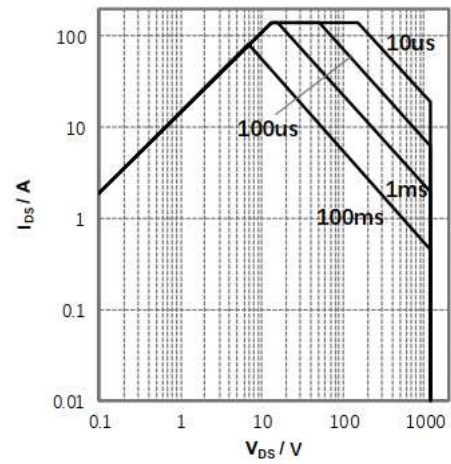


Figure 26. Safe Operating Area

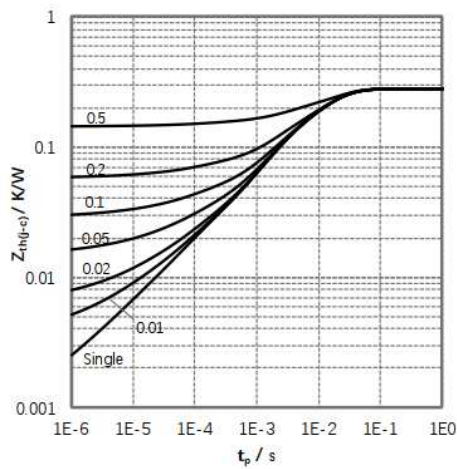
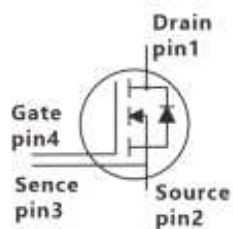


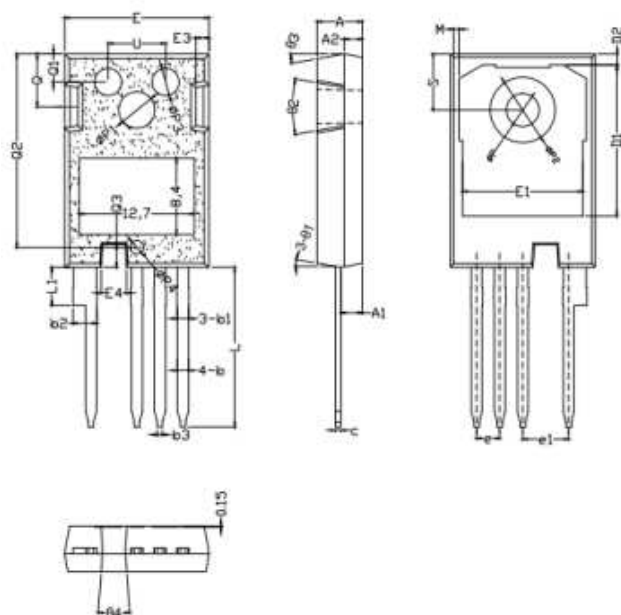
Figure 27. Transient Thermal Impedance (Junction-Case)



- Circuit diagram



- TO-247-4L Package outlines : Dimensions in (mm)



SYMBOL	mm		
	MIN	NOM	MAX
✱A	4.83	5.02	5.21
✱A1	2.29	2.42	2.54
A2	1.91	2.00	2.16
✱b	1.07	1.20	1.33
✱b1	1.07	1.23	1.40
✱b2	2.39	2.67	2.94
b3	0.45	0.60	0.75
✱c	0.55	0.60	0.68
✱D	23.30	23.45	23.60
D1	16.35	16.65	16.95
D2	0.95	1.19	1.25
✱E	15.75	15.94	16.13
E1	13.00	13.25	13.45
E2	4.20	4.60	5.00
E3	1.00	1.45	1.90
E4	2.40	2.80	3.20
✱e	2.50	2.54	2.58
✱e1	5.03	5.08	5.13
✱L	17.27	17.57	17.82
✱L1	-	-	4.37
M	0.40	0.60	0.80
✱ΦF	3.51	3.61	3.71
ΦP1	3.80	4.00	4.20
ΦP2	7.03	7.18	7.33
ΦP3	2.80	3.00	3.20
ΦP4	1.30	1.50	1.70
Q	5.49	5.79	6.00
Q1	2.80	3.10	3.40
Q2	19.95	21.25	21.55
Q3	2.35	2.50	2.65
S	6.04	6.17	6.30
U	6.05	6.35	6.55
θ1	6°	10°	13°
θ2	16°	20°	24°
θ3	6°	10°	13°
θ4	5°	8°	11°

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